

ABSTRACT

A bonding pad for an integrated circuit, having a conductive base layer. The conductive base layer has slots formed in it, where the slots extend completely through the conductive base layer. An insulating layer is disposed on top of the conductive base layer. The insulating layer protrudes into the slots of the conductive base layer. The
5 insulating layer also includes a low k material. A conductive top layer is disposed on top of the insulating layer.

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